

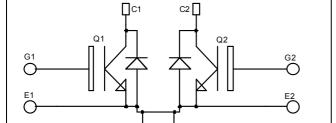
Dual common source NPT IGBT Power Module

$$V_{CES} = 600V$$

 $I_{C} = 180A$ @ $Tc = 80$ °C

Application

- AC Switches
- Switched Mode Power Supplies
- Uninterruptible Power Supplies



G2 🛭

Features

- Non Punch Through (NPT) Fast IGBT
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 100 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

NTC2

0

6

C2

C2

NTC2 # NTC1 #

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Easy paralleling due to positive TC of VCEsat
- Low profile
- · RoHS compliant

Absolute maximum ratings

0

C1

NTC1

Symbol	Parameter	Max ratings	Unit	
V_{CES}	Collector - Emitter Breakdown Voltage		600	V
T	Continuous Collector Current	$T_c = 25^{\circ}C$	220	
I_{C}	Continuous Conector Current	$T_c = 80$ °C	180	A
I_{CM}	Pulsed Collector Current	$T_c = 25^{\circ}C$	630	
V_{GE}	Gate – Emitter Voltage		±20	V
P_{D}	Maximum Power Dissipation	$T_c = 25^{\circ}C$	833	W
RBSOA	Reverse Bias Safe Operating Area	$T_j = 150^{\circ}C$	400A @ 600V	

These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0V$	$T_i = 25$ °C			300	μA
ICES	Zero Gate voltage Collector Current	$V_{CE} = 600V$	$T_{i} = 125^{\circ}C$			1000	μА
17	Collector Emitter saturation Voltage	$V_{GE} = 15V$	$T_j = 25$ °C		2.0	2.5	V
$V_{CE(sat)}$	Collector Emitter saturation voltage	$I_{\rm C} = 180A$	$T_j = 125$ °C		2.2		V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 2mA$		3		5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20 \text{ V}, V_{CE} = 0 \text{ V}$				±200	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
Cies	Input Capacitance	$V_{GE} = 0V$ $V_{CE} = 25V$ $f = 1MHz$			8.6		nF
C_{oes}	Output Capacitance				0.94		
C_{res}	Reverse Transfer Capacitance				0.8		
Q_g	Total gate Charge	$V_{GS} = 15V$ $V_{Bus} = 300V$			660		nC
Q_{ge}	Gate – Emitter Charge				580		
Q_{gc}	Gate – Collector Charge	$I_{\rm C} = 180 {\rm A}$			400		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switch	ning (25°C)		26		
$T_{\rm r}$	Rise Time	$V_{GE} = 15V$			25		
$T_{d(off)}$	Turn-off Delay Time	$V_{Bus} = 400V$ $I_{C} = 180A$		150		ns	
T_{f}	Fall Time	$R_G = 2.5 \Omega$		30			
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{GE} = 15V$ $V_{Bus} = 400V$ $I_{C} = 180A$			26		ns
$T_{\rm r}$	Rise Time				25		
$T_{d(off)}$	Turn-off Delay Time				170		
$T_{\rm f}$	Fall Time	$R_G = 2.5 \Omega$			40		
Eon	Turn-on Switching Energy	$V_{GE} = 15V$ $V_{Bus} = 400V$	$T_j = 125$ °C		8.6		I
E_{off}	Turn-off Switching Energy	$I_C = 180A$ $R_G = 2.5 \Omega$	$T_j = 125$ °C		7		mJ

Reverse diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Test Conditions		Тур	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V
I_{RM}	Maximum Reverse Leakage Current	$V_{R} = 600 V$	$T_j = 25^{\circ}C$			750	μΑ
1RM	Waximum Reverse Leakage Current	VR OOOV	$T_j = 125$ °C			1500	μΑ
I_F	DC Forward Current		$T_c = 70$ °C		120		A
	Diode Forward Voltage	$I_F = 120A$			1.6	1.8	
$V_{\rm F}$		$I_F = 240A$			1.9		V
		$I_F = 120A$	$T_j = 125$ °C		1.4		
t_{rr}	Reverse Recovery Time	$I_F = 120A$ $V_R = 400V$	$T_j = 25$ °C		85		ns
ι _{rr}			$T_{j} = 125^{\circ}C$		160		113
Q _{rr}	Reverse Recovery Charge	$di/dt = 800A/\mu s$	$T_j = 25^{\circ}C$		520		nC
			$T_{j} = 125^{\circ}C$		2800		110



Thermal and package characteristics

Symbol	Characteristic			Min	Тур	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance	IGBT			0.15	°C/W	
KthJC		Diode			0.32	C/ VV	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range		-40		150		
T_{STG}	Storage Temperature Range		-40		125	°C	
$T_{\rm C}$	Operating Case Temperature					100	
Torque	Mounting torque	To Heatsink	M5	2.5		4.7	N.m
Wt	Package Weight					160	g

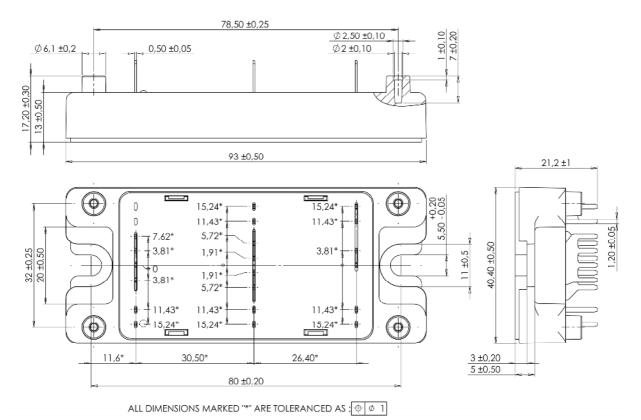
 $Temperature \ sensor \ NTC \ (\text{see application note APT0406 on www.microsemi.com for more information}). \\$

Symbol	Characteristic	Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C		50		kΩ
B 25/85	$T_{25} = 298.15 \text{ K}$		3952		K

$$R_{T} = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]} \quad \text{T: Thermistor temperature}$$

$$R_{T}: \text{ Thermistor value at T}$$

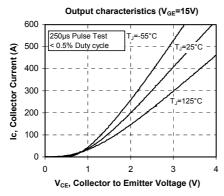
SP4 Package outline (dimensions in mm)

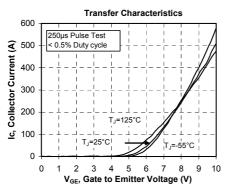


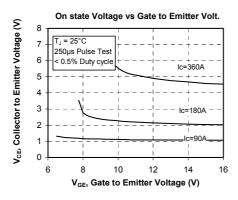
See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

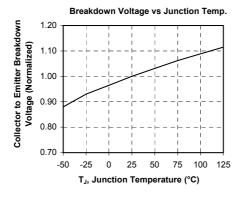


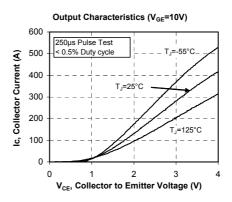
Typical Performance Curve

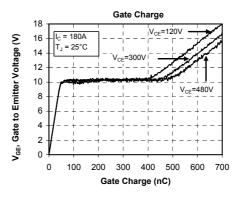


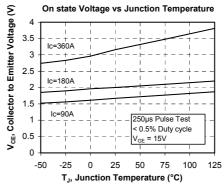


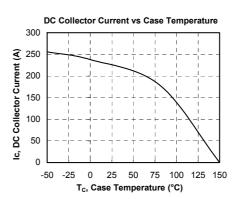




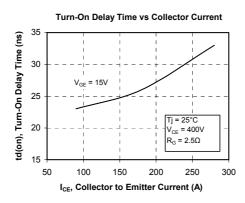


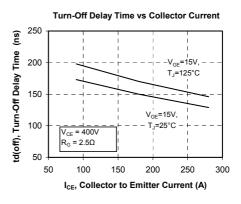


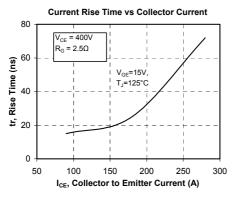


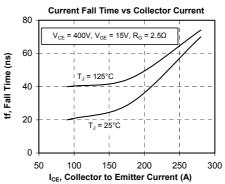


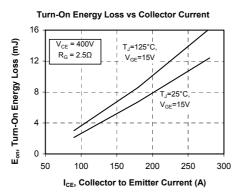


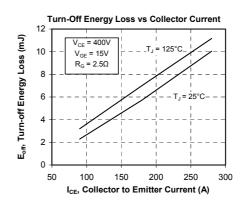


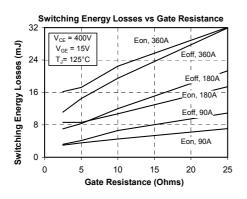


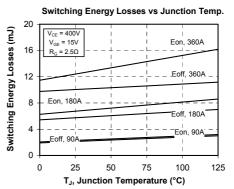




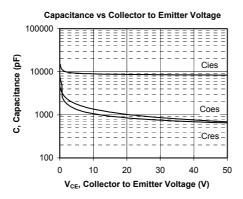


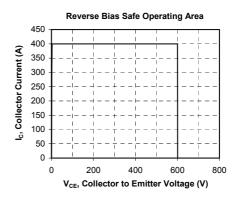


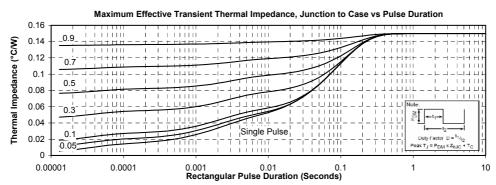


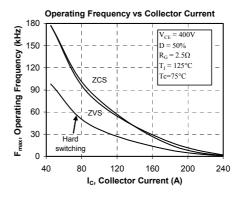














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